

WHAT IS CLAIMED IS:

1. A digital micro-mirror device (DMD) packages, comprising:  
a base substrate having a top surface and a bottom surface;  
5 a metallic layer formed on the top surface of the base substrate;  
a metallic adhesive formed on the metallic layer;  
a semiconductor chip mounted on the metallic adhesive, the base substrate electrically  
connected with the semiconductor chip;  
one or more mirrors mounted on the semiconductor chip;  
10 a hermetic sealing means covering the semiconductor chip including the one more  
mirrors.

2. The DMD package of claim 1, which further comprises a heat sink attached on  
the bottom surface of the base substrate.